

Press Release

Heraeus Electronics to Share Cutting-Edge Packaging Insights in Three Presentations at CIPS 2026

Hanau, February 2026 – Heraeus Electronics is proud to announce its participation at the 2026 CIPS Conference & Exhibition in Dresden, March 10–12. The company will deliver three technical presentations and host a tabletop exhibit, showcasing its latest advances in power electronics packaging materials and technologies. is one of the most important international forums for power electronics. With a strong technical program and high international participation, the conference places special emphasis on packaging innovations.

Heraeus Electronics Presentations Include:**Tuesday, March 10 – General Aspects of Packaging, Poster Area (15:50–18:20)**

- *A New Approach Towards Cost-Effective Sintering – Microstructural Investigations of Aged SiC Power Modules*

Heraeus Electronics researchers, in collaboration with Fraunhofer IMWS and Schaeffler Group, will discuss SiC MOSFET chips pressure-sintered with silver and copper paste. Their analysis, prepared within the German funded project “KuSIn”, shows that sintered layers maintain microstructural integrity after thermal and power cycling, providing insight into reliable high-performance module fabrication.

Wednesday, March 11 – Module Packaging, Cooling, and Failure Analysis II (11:40)

- *Sintering-Induced Fracture in WBG Dies Based on Substrate Choice*

This presentation examines the reliability of GaN and SiC devices after sintering, highlighting how substrate choice influences die cracking and mechanical stress. Results support the development of accelerated reliability testing methods for wide bandgap semiconductors in high-performance power electronics and were performed within the EU project “ALL2GaN”.

Wednesday, March 11 – Reliability of Substrates and Bonding (13:50)

- *Electrical Lifetime Prediction of Various Si_3N_4 Ceramic Substrates for Power Modules*

Heraeus Electronics researchers will present a comparative study of silicon nitride ceramics for power module substrates, detailing AC test regimes, partial discharge behavior, and voltage-dependent lifetime predictions. The findings provide practical guidance for selecting and qualifying substrate materials in demanding applications.

Heraeus Electronics will also exhibit at a **tabletop in the exhibition area**, where attendees can talk to experts and learn more about the company's solutions for module packaging, e.g. sintering and bonding materials, and substrate technologies.

For more information on Heraeus Electronics, visit www.heraeus-electronics.com.

About Heraeus

Heraeus is a globally active, family-owned technology group. Based in Hanau, Germany, the company comprises 15 operating companies whose products and services span the Business Areas of Metals & Recycling, Healthcare, Semiconductor & Electronics, and Industrials. In fiscal year 2024, Heraeus generated revenues of €29.4 billion and employed roughly 15,200 people across 40 countries. This makes Heraeus one of the top ten largest family-owned enterprises in Germany.

MATERIALS. INNOVATIONS. FOR GENERATIONS.

About Heraeus Electronics

Heraeus Electronics is a materials innovation partner for the electronics industry with global reach and local presence. The

company develops material solutions for the automotive, power electronics and advanced semiconductor packaging market and offers its customers a broad product portfolio – from materials and material systems to services.

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